



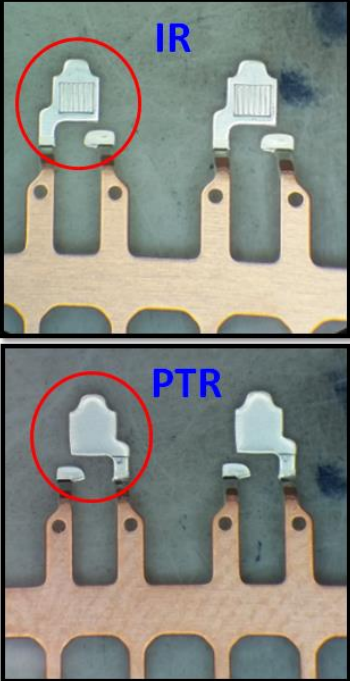
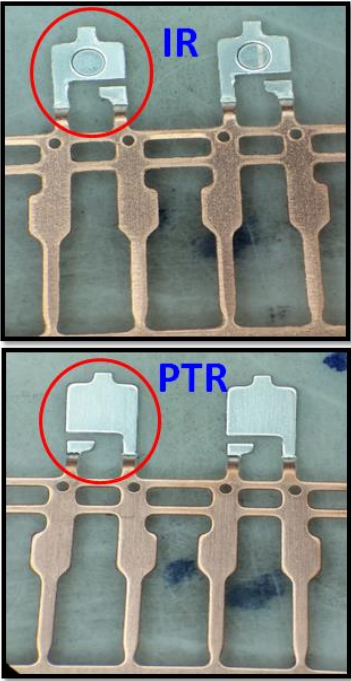
Title of Change:	To convert H11AD9X-5660 series + MCT9001x series from Single to Matrix Leadframe	
Proposed first ship date:	11 April 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or khaicheong.yau@onsemi.com	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or changkit.mok@onsemi.com	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>	
Change Part Identification:	It will be identified by implementation datecode.	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Liteon Bangkok



Description and Purpose:

- The Matrix unit will be in
1. Laser mark instead of inked mark
 2. Bigger DAP
 3. Has an unique mold ID stamp

Reason : Leadframe vendor would not want to continue with the support of non-matrix leadframe

	Before Change Description	After Change Description
LeadFrame	Single 	Matrix (Bigger DAP) 
Mold Compound	Without Mold ID	With Mold ID

	From	To
Product marking change	Ink Mark	Laser Mark



Reliability Data Summary:

DEVICE: MCT9001
PACKAGE: PDIP 8 (Black Package)

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=100°C, biased	1008 hours	0/240
HTSL	JESD22-A103	Ta= 150°C, unbiased	1008 hours	0/240
PC	J-STD-020 JESD-A113	MSL 1@260°C	-	0/480
TC + PC	JESD22-A104	Ta= -55°C to +125°C	1000 cycles	0/240
THB + PC	JESD22-A101	Ta=85°C / 85% RH, biased	1008 hours	0/240
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30
SD	JSTD002	Ta = 245C, 10 sec	-	0/10

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

Part Number	Qualification Vehicle
MCT9001	MCT9001
MCT9001S	
MCT9001SD	



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle
MCT9001	MCT9001-ND	MCT9001
MCT9001S		MCT9001
MCT9001SD		MCT9001